







CSD18536KCS SLPS532C - JULY 2014 - REVISED MARCH 2024

CSD18536KCS 60V N-Channel NexFET™ Power MOSFET

1 Features

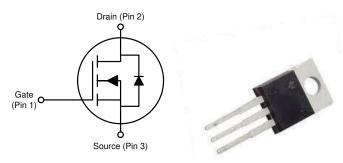
- Ultra-low \mathbf{Q}_{g} and \mathbf{Q}_{gd} Low thermal resistance
- Avalanche rated
- Pb-free terminal plating
- · RoHS compliant
- Halogen free
- TO-220 plastic package

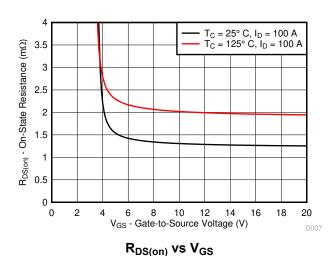
2 Applications

- Secondary side synchronous rectifier
- Motor control

3 Description

This 60V, 1.3mΩ, TO-220 NexFET™ power MOSFET is designed to minimize losses in power conversion applications.





Product Summary

T _A = 25°	С	TYPICAL VA	UNIT		
V _{DS}	Drain-to-Source Voltage 60				
Qg	Gate Charge Total (10V) 108				
Q _{gd}	Gate Charge Gate-to-Drain	14		nC	
Б	Drain-to-Source On-Resistance	V _{GS} = 4.5V 1.7		mΩ	
R _{DS(on)}	Dialii-to-Source Off-Resistance	V _{GS} = 10V 1.3		mΩ	
V _{GS(th)}	Threshold Voltage	1.8		V	

Ordering Information

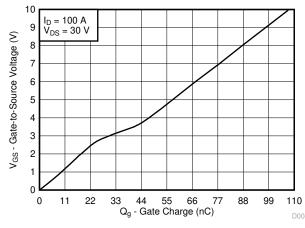
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Device ⁽¹⁾		Package	Media	Qty	Ship	
	CSD18536KCS	TO-220 Plastic Package	Tube	50	Tube	

For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

	Absolute maximum ratings								
T _A = 2	25°C	VALUE	UNIT						
V _{DS}	Drain-to-Source Voltage	60	V						
V _{GS}	Gate-to-Source Voltage	±20	V						
	Continuous Drain Current (Package limited)	200							
I _D	Continuous Drain Current (Silicon limited), T _C = 25°C	349	A						
	Continuous Drain Current (Silicon limited), T _C = 100°C	247							
I _{DM}	Pulsed Drain Current (1)	400	Α						
P _D	Power Dissipation	375	W						
T _J , T _{stg}	Operating Junction and Storage Temperature Range	-55 to 175	°C						
E _{AS}	Avalanche Energy, single pulse I_D = 128A, L = 0.1mH, R_G = 25 Ω	819	mJ						

Max $R_{\theta JC}$ = 0.4°C/W, pulse duration ≤100µs, duty cycle ≤1%. (1)



Gate Charge



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4 Specifications

4.1 Electrical Characteristics

(T_A = 25°C unless otherwise stated)

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
STATIC	CHARACTERISTICS		<u>'</u>		
BV _{DSS}	Drain-to-Source Voltage	V _{GS} = 0V, I _D = 250μA	60		V
I _{DSS}	Drain-to-Source Leakage Current	V _{GS} = 0V, V _{DS} = 48V		1	μA
I _{GSS}	Gate-to-Source Leakage Current	V _{DS} = 0V, V _{GS} = 20V		100	nA
$V_{GS(th)}$	Gate-to-Source Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	1.4 1.8	2.2	V
Б	Drain-to-Source On-Resistance	V _{GS} = 4.5V, I _D = 100A	1.7	2.2	mΩ
R _{DS(on)}	Drain-to-Source On-Resistance	V _{GS} = 10V, I _D = 100A	1.3	1.6	mΩ
9 _{fs}	Transconductance	V _{DS} = 6V, I _D = 100A	312		S
DYNAM	IC CHARACTERISTICS				
C _{iss}	Input Capacitance		8790	11430	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 30V, f = 1MHz$	1410	1840	pF
C _{rss}	Reverse Transfer Capacitance		39	51	pF
R _G	Series Gate Resistance		0.7	1.4	Ω
Qg	Gate Charge Total (10V)		108	140	nC
Q_{gd}	Gate Charge Gate-to-Drain	V = 20V L = 400A	14		nC
Q _{gs}	Gate Charge Gate-to-Source	$V_{DS} = 30V, I_{D} = 100A$	18		nC
Q _{g(th)}	Gate Charge at V _{th}		17		nC
Q _{oss}	Output Charge	V _{DS} = 30V, V _{GS} = 0V	230		nC
t _{d(on)}	Turn On Delay Time		11		ns
t _r	Rise Time	V _{DS} = 30V, V _{GS} = 10 V,	5		ns
t _{d(off)}	Turn Off Delay Time	$I_{DS} = 100A$, $R_G = 0\Omega$	24		ns
t _f	Fall Time		4		ns
DIODE (CHARACTERISTICS	·			
V _{SD}	Diode Forward Voltage	I _{SD} = 100A, V _{GS} = 0V	0.9	1.0	V
Q _{rr}	Reverse Recovery Charge	V _{DS} = 30V, I _F = 100A,	323		nC
t _{rr}	Reverse Recovery Time	di/dt = 300A/μs	86		ns

4.2 Thermal Information

(T_A = 25°C unless otherwise stated)

	THERMAL METRIC	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-Case Thermal Resistance			0.4	°C/W
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance			62	C/VV

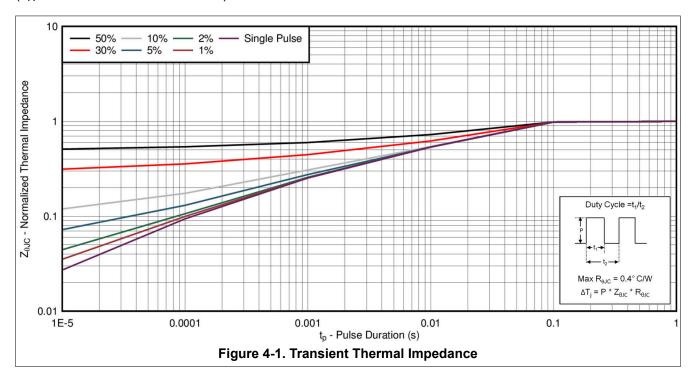
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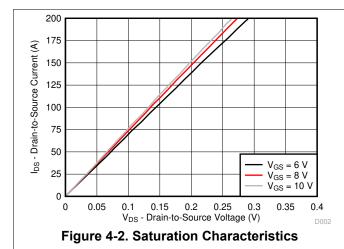
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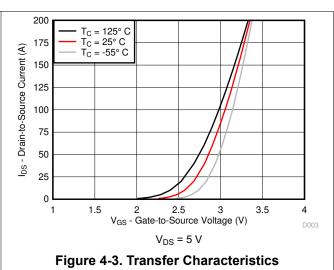


4.3 Typical MOSFET Characteristics

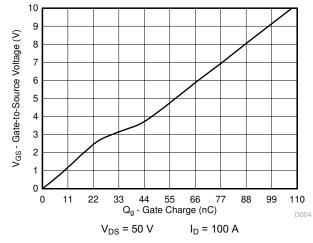
 $(T_A = 25^{\circ}C \text{ unless otherwise stated})$







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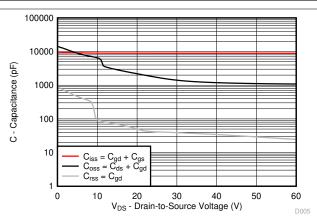
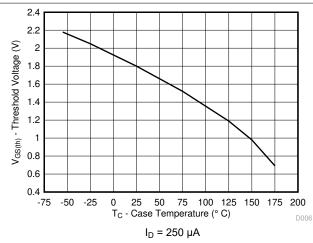


Figure 4-5. Capacitance





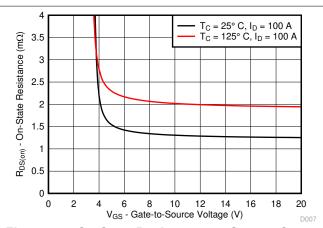
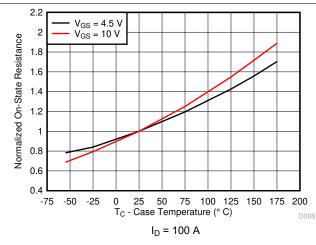


Figure 4-7. On-State Resistance vs Gate-to-Source Voltage

Figure 4-6. Threshold Voltage vs Temperature



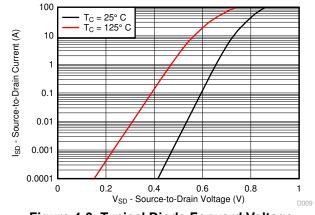
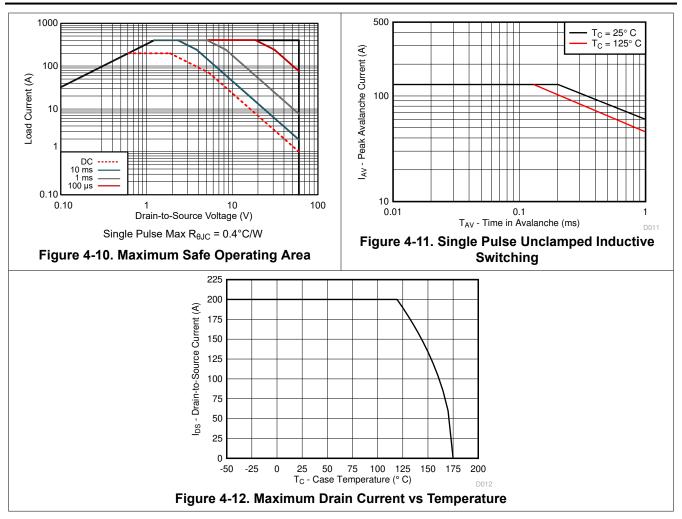


Figure 4-9. Typical Diode Forward Voltage

Figure 4-8. Normalized On-State Resistance vs
Temperature







5 Device and Documentation Support

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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5.3 Trademarks

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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

6 Revision History

Changes from Revision B (June 2023) to Revision C (March 2024) Changes from Revision A (December 2017) to Revision B (June 2023) Page Updated Figure 4-104 Changes from Revision * (March 2015) to Revision A (December 2017) Page Changed C_{OSS} values From: TYP = 1700pF MAX = 2210pF To: TYP = 1410 pF MAX = 1840pF in *Dynamic* Changed Q_d values From: TYP = 83nC MAX = 108nC To: TYP = 108nC MAX = 140nC in the *Dynamic* Updated Figure 4-4.4

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7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CSD18536KCS	Active	Production	TO-220 (KCS) 3	50 TUBE	ROHS Exempt	SN	N/A for Pkg Type	-55 to 175	CSD18536KCS
CSD18536KCS.B	Active	Production	TO-220 (KCS) 3	50 TUBE	ROHS Exempt	SN	N/A for Pkg Type	-55 to 175	CSD18536KCS

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CSD18536KCS	KCS	TO-220	3	50	532	34.1	700	9.6
CSD18536KCS.B	KCS	TO-220	3	50	532	34.1	700	9.6



TO-220



NOTES:

- 1. Dimensions are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. Reference JEDEC registration TO-220.



TO-220



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